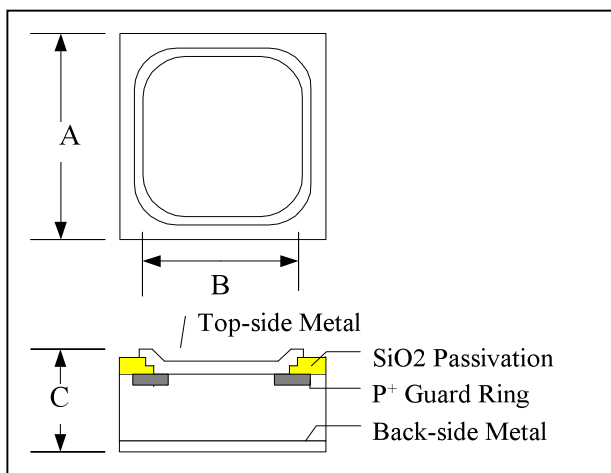


<b>ELECTRICAL CHARACTERISTICS</b>	<b>SYM</b>	<b>Spec. Limit</b>	<b>UNIT</b>
Reverse Breakdown Voltage: Ir=0.10mA	VBRM	105	Volt
Average Rectified Forward Current	IFAV (1)	5.0	Amp
Maximum Instantaneous Forward Voltage			
Ta=25°C	VF MAX @ 5 Amp	0.790	Volt
Maximum Instantaneous Reverse Current @VR			
Ta=25°C	IR MAX	20	uA
<b>MAXIMUM RATINGS</b>			
Nonrepetitive Peak Surge Current			
Semi-Sine Wave, Duty = 8.3ms · 1cycle	IFSM	150	Amp
Operating Junction Temperature	Tj	150	°C
Storage Temperatures	TSTG	-50 to +150	°C

1. Specification is applied to die only. Actual performance may degrade when assembled. BW does not guarantee device performance after assembly.
2. Suggest to storage in Nitrogen cabinet, 45-60% RH, 22-26 °C for 6 months.
3. Data sheet information is subjected to change without notice.
4. Suggest Soldering profile (Pb92.5%,5%Sn,Ag2.5%): Soldering peak Temp. 340~350 °C 3~5min.

DICE OUTLINE DRAWING



<b>DIM</b>	<b>ITEM</b>	<b>μ m</b>	<b>Mil</b>
A	Die Size	1650	65.00
B	Top Metal Pad Size	1450	57.08
C	Thickness	280	11.00

(1)Cutting street width is around 60μm.  
(2)Both of top-side and back-side metals are Ti/Ni/Ag.  
(3) Top-side Ti/Ni thk: 0.42um, Ag thk: 3.5um  
(4) Thickness(C) tolerance: +/-10um